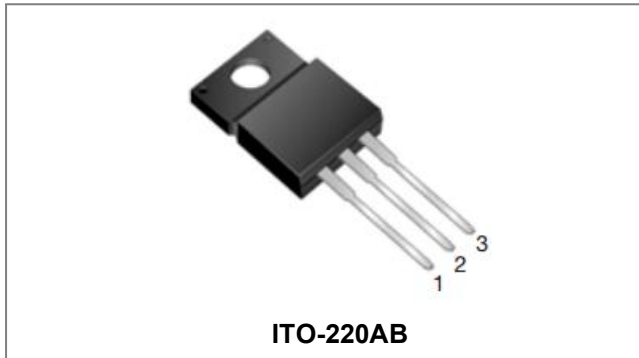


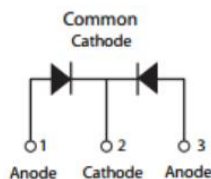
## SDURF2020CT(CTR) ULTRAFAST RECTIFIER



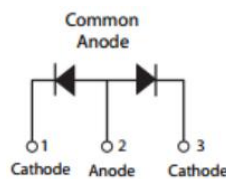
### Applications

- Antiparallel diode for high frequency switching devices
- Anti saturation diode
- Snubber diode
- Free wheeling diode in converters and motor control circuits
- Rectifiers in switch mode power supplies (SMPS)
- Inductive heating and melting
- Uninterruptible power supplies (UPS)
- Ultrasonic cleaners and welders

### Circuit Diagram



SDURF2020CT



SDURF2020CTR

### Features

- Ultra-Fast switching
- High current capability
- Low reverse leakage current
- High surge current capability
- This is a Pb - free device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

### Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage	$V_{RRM}$	-	200	V
Working Peak Reverse Voltage	$V_{RWM}$			
DC Blocking Voltage	$V_R$			
Average Rectified Forward Current	$I_{F(AV)}$	50% duty cycle @ $T_c=100^\circ\text{C}$ , rectangular wave form	10(Per Leg) 20(Per Device)	A
Peak One Cycle Non-Repetitive Surge Current(Per Leg)	$I_{FSM}$	8.3ms, Half Sine pulse	125	A

### Electrical Characteristics:

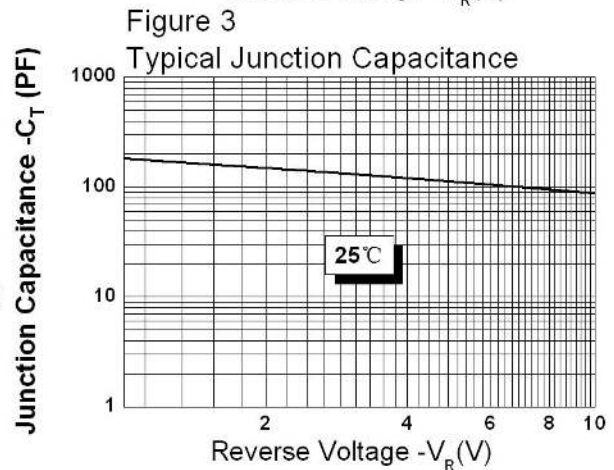
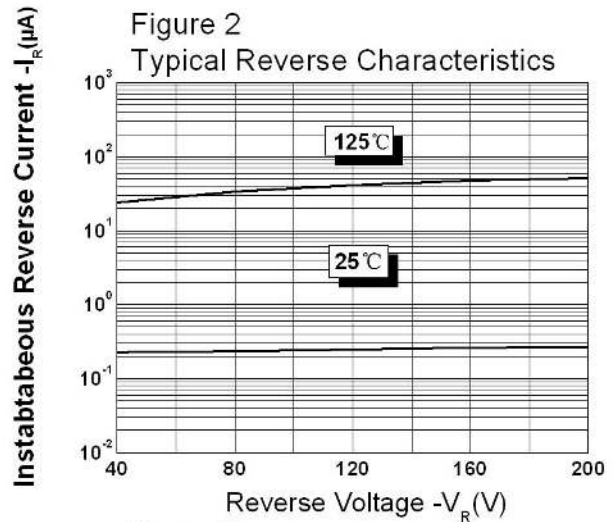
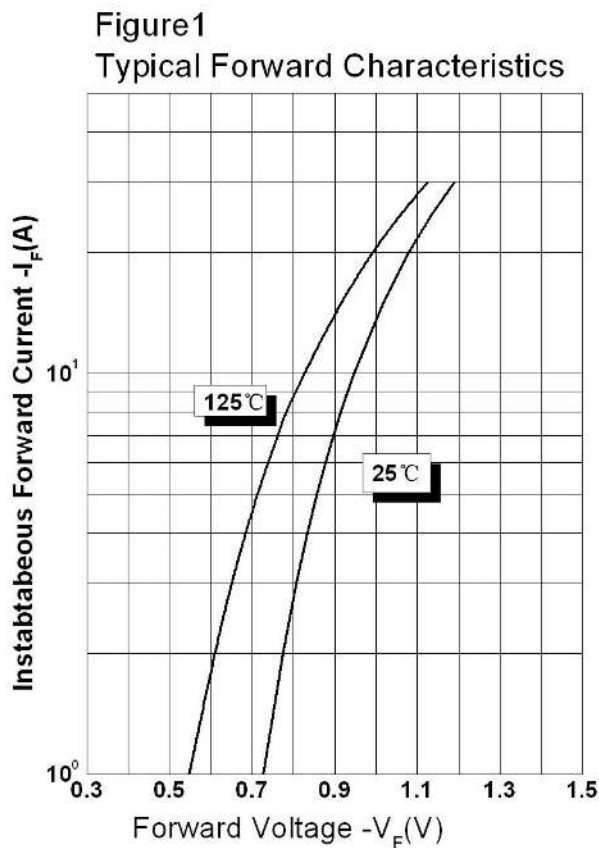
Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop(Per Leg)*	$V_{F1}$	@ $I_F = 10\text{A}$ , Pulse, $T_J = 25^\circ\text{C}$	0.94	1.15	V
Reverse Current(Per Leg)*	$I_{R1}$	@ $V_R = \text{rated } V_R$ $T_J = 25^\circ\text{C}$	0.3	15	$\mu\text{A}$
	$I_{R2}$	@ $V_R = \text{rated } V_R$ $T_J = 125^\circ\text{C}$	50	250	$\mu\text{A}$
Reverse Recovery Time(Per Leg)	$t_{rr1}$	$I_F=500\text{mA}$ , $I_R=1\text{A}$ , and $I_m=250\text{mA}$	32	35	ns

\* Pulse width < 300  $\mu\text{s}$ , duty cycle < 2%

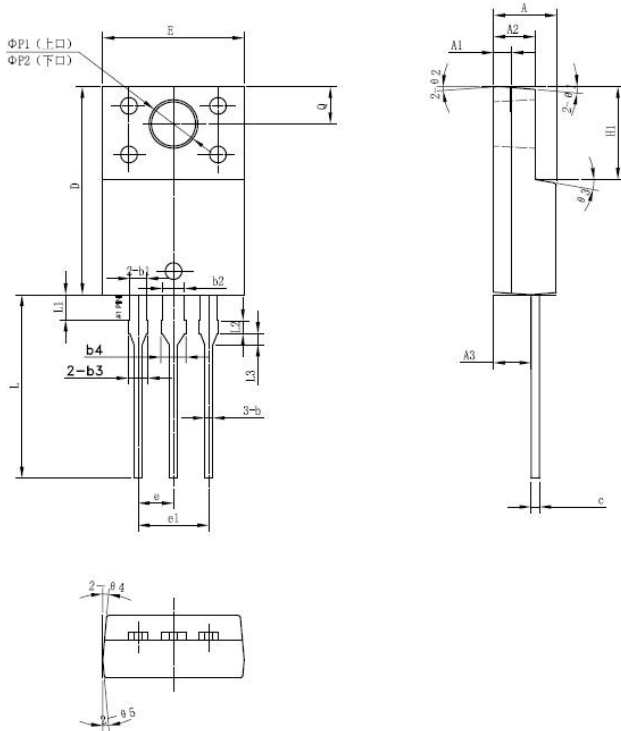
**Thermal-Mechanical Specifications:**

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	$T_J$	-	-55 to +150	$^{\circ}\text{C}$
Storage Temperature	$T_{\text{stg}}$	-	-55 to +150	$^{\circ}\text{C}$
Typical Thermal Resistance Junction to Case	$R_{\theta\text{JC}}$	DC operation	3.5	$^{\circ}\text{C}/\text{W}$
Typical Thermal Resistance Junction to Ambient	$R_{\theta\text{JA}}$	DC operation	50	$^{\circ}\text{C}/\text{W}$
Approximate Weight	wt	-	2	g
Case Style	ITO-220AB			

**Ratings and Characteristics Curves**

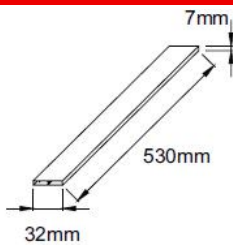


**Mechanical Dimensions ITO-220AB**



SYMBOL	Millimeters		
	MIN.	TYP.	MAX.
A	4.30	4.50	4.70
A1	1.10	1.30	1.50
A2	2.80	3.00	3.20
A3	2.50	2.70	2.90
b	0.50	0.60	0.75
b1	1.10	1.20	1.35
b2	1.50	1.60	1.75
b3	1.20	1.30	1.45
b4	1.60	1.70	1.85
c	0.50	0.60	0.75
D	14.80	15.00	15.20
E	9.96	10.16	10.36
e		2.55	
e1		5.10	
H1	6.50	6.70	6.90
L	12.70	13.20	13.70
L1	1.60	1.80	2.00
L2	0.80	1.00	1.20
L3	0.60	0.80	1.00
ΦP1(上口)	3.30	3.50	3.70
ΦP2(下口)	2.99	3.19	3.39
Q	2.50	2.70	2.90
Θ1		5°	
Θ2		4°	
Θ3		10°	
Θ4		5°	
Θ5		5°	

**Tube Specification**

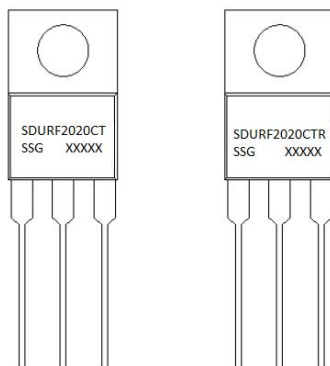


**Ordering Information**

Device	Package	Shipping
SDURF2020CT(CTR)	ITO-220AB (Pb-Free)	50 pcs/ tube

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

**Marking Diagram**



Where XXXXX is YYWWL

- SDUR = Device Type
- F = Package type
- 20 = Forward Current (20A)
- 20 = Reverse Voltage (200V)
- CT(CTR) = Configuration
- SSG = SSG
- YY = Year
- WW = Week
- L = Lot Number

**Cautions:** Molding resin  
Epoxy resin UL:94V-0



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